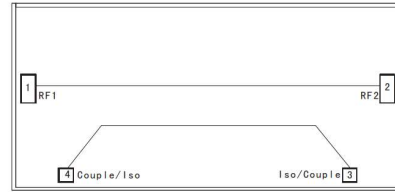


Performance

- Frequency: 5~6GHz
- Coupling: 20dB
- Coupling Flatness: 0.5dB
- Chip size: 2.6*1.3*0.1mm

Function Diagram

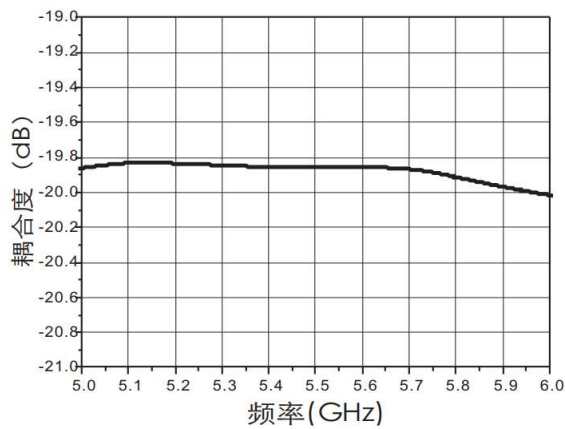


Electrical Specifications (Ta=+25°C, 50Ω system)

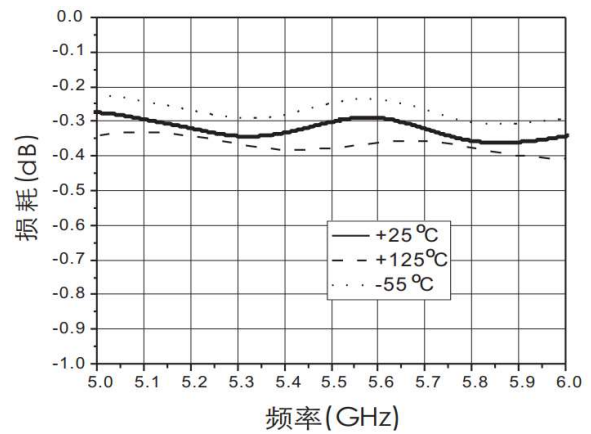
Parameter	Min	Typical	Max	Unit
Frequency Range		5~6		GHz
Coupling	-	19.8	-	dB
Insertion Loss	-	0.3	-	dB
Input Return loss	-	21	-	dB
Thru Output Return loss	-	21	-	dB
Coupling Output Return loss	-	21	-	dB
Isolation	-	29	-	dB

Test Curves (Die chip + Bonding line test)

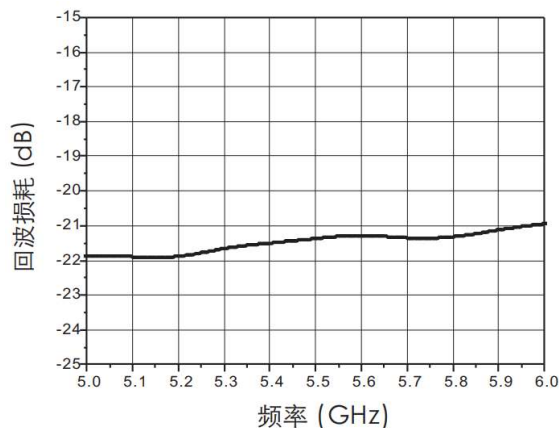
Coupling vs. Freq



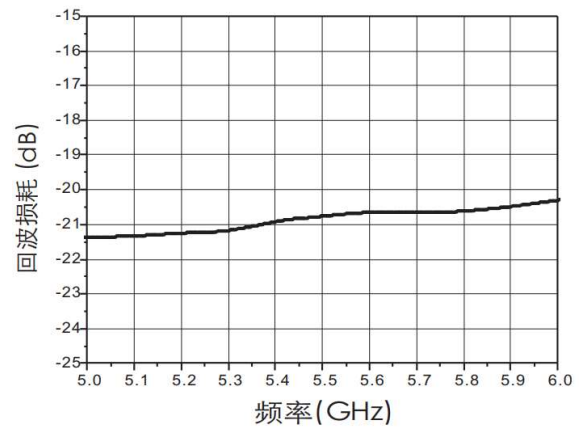
Insertion loss vs. Freq

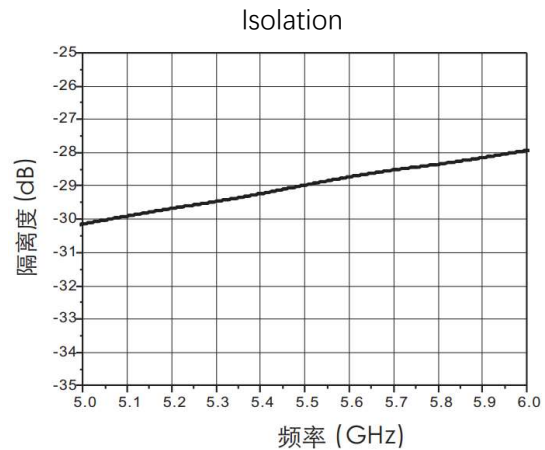
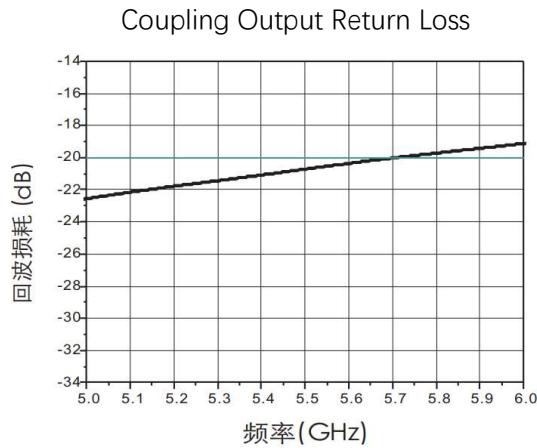


Input Return Loss vs. Freq



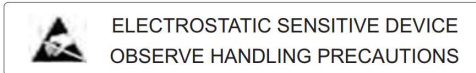
Thru output Return loss vs. Freq



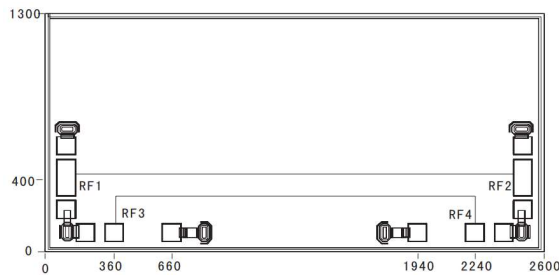


Absolute Rating

Max Input Power	10W
Static Protection (HBM)	Class 1A
Storage Temperature	-65~+150°C
Operating Temperature	-55~+125°C



Outline Size



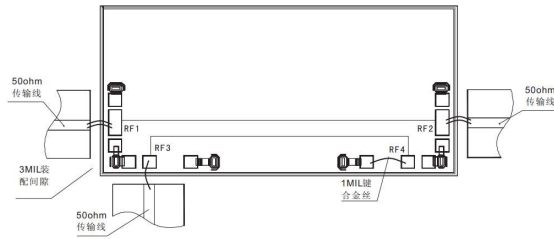
Note:

1. Unit: μm
2. Bottom side is gold plated
3. Bottom side is GND
4. Bonding pads is gold plated,
Pad size: 1,2: $0.1 \times 0.2\text{mm}$
3,4,5,6: $0.1 \times 0.1\text{mm}$
5. Don't bonding on thru holds
6. Tolerance: $\pm 50\mu\text{m}$

Bonding Pads Definition

Number	Symbol	Description
1	RFin	RF input port, 50ohm
2	RFout	RF output port, 50 ohm
3,4	Couple/ISO	Choose either one as couple output port, another port connect to 50 Ω resistor pad
5,6	LOAD	Resistor pads

Application (Chip left side couple output)



Application (Chip right side couple output)

